

Vishay Siliconix

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (Ω) Max.	I _D (A) ^a	Q _g (Typ.)			
20	0.73 at $V_{GS} = 4.5 \text{ V}$	1				
	0.87 at V _{GS} = 2.5 V	0.92	0.5 nC			
	1.10 at V _{GS} = 1.8 V	0.82	0.5110			
	1.80 at V _{GS} = 1.5 V	0.64				

PowerPAK® 0806 Single

Bottom View

Marking Code: C
Ordering Information:

Top View

SiUD402ED-T1-GE3 (Lead (Pb)-free and halogen-free)

FEATURES

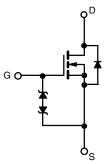
- TrenchFET® power MOSFET
- Ultra small 0.8 mm x 0.6 mm outline
- Ultra thin 0.4 mm max. height
- 100 % R_g tested
- Typical ESD protection 2000 V (HBM)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

RoHS COMPLIANT HALOGEN

FREE

APPLICATIONS

- Load switch
- · High speed switching
- DC/DC converters
- For smart phones, tablet PCs and mobile computing
- Small signal switching



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	20	V		
Gate-Source Voltage		V_{GS}	± 8	7 °		
	T _A = 25 °C		1 ^a			
Continuous Drain Correct /T 150 °C)	T _A = 70 °C	1 ,	0.8 ^a			
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	0.35 ^b			
	T _A = 70 °C	1	0.28 ^b	Α		
Pulsed Drain Current (t = 100 μs)		I _{DM}	1.4			
Osalis a a Osa wa Buis Bisda Osaad	T _A = 25 °C		1 ^a			
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	0.37 ^b			
	T _A = 25 °C		1.25 ^a	W		
Manipular Danier Dispiration	T _A = 70 °C	1 5	0.8 ^a			
Maximum Power Dissipation	T _A = 25 °C	P _D	0.37 ^b			
	T _A = 70 °C	1	0.24 b			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	- °C		
Soldering Recommendations (Peak Temperature) ^c			260			

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient a, d	t < 5 s	В	80	100	°C/W		
Maximum Junction-to-Ambient b, e	1 ≥ 3 8	R _{thJA}	265	335	C/VV		

Notes

- a. Surface mounted on 1" x 1" FR4 board with full copper, t = 5 s.
- b. Surface mounted on 1" \times 1" FR4 board with minimum copper, t = 5 s.
- c. Refer to IPC/JEDEC® (J-STD-020), no manual or hand soldering.
- d. Maximum under steady state conditions is 135 °C/W.
- e. Maximum under steady state conditions is 400 °C/W.

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SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static					•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20	-	-	V		
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 A	1	18	-	mV/°C		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-1.9	-			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	0.4	-	0.9	V		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 0.5			
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 10	μΑ		
Zeve Cata Valtage Drain Comment		V _{DS} = 20 V, V _{GS} = 0 V	-	-	1			
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10			
On-State Drain Current ^a			1	-	-	Α		
		$V_{GS} = 4.5 \text{ V}, I_D = 0.2 \text{ A}$	-	0.57	0.73	1		
Drain Caura On State Besistance 8	_B	$V_{GS} = 2.5 \text{ V}, I_D = 0.1 \text{ A}$	-	0.67	0.87			
Drain-Source On-State Resistance a	R _{DS(on)}	V _{GS} = 1.8 V, I _D = 0.02 A	-	0.80	1.10	Ω		
		V _{GS} = 1.5 V, I _D = 0.01 A	-	0.90	1.80	1		
Forward Transconductance a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 0.2 \text{ A}$	-	1.2	-	S		
Dynamic ^b								
Input Capacitance	C _{iss}		-	16	-			
Output Capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	1	7.5	-	pF		
Reverse Transfer Capacitance	C _{rss}		-	3.5	-			
Tabal Oata Obaasa	Qg	V _{DS} = 10 V, V _{GS} = 8 V, I _D = 0.2 A	-	0.75	1.20	nC		
Total Gate Charge			-	0.50	0.75			
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.2 \text{ A}$	-	0.09	-			
Gate-Drain Charge	Q _{gd}		-	0.09	-			
Gate Resistance	R _g	f = 1 MHz	3	24	50	Ω		
Turn-On Delay Time	t _{d(on)}		-	7	15			
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_{L} = 50 \Omega$	-	10	20	ns		
Turn-Off Delay Time		$I_D \cong 0.2 \text{ A}, V_{GEN} = 4.5 \text{ V}, Rg = 1 \Omega$	-	23	50			
Fall Time	t _f		-	7	15			
Turn-On Delay Time	t _{d(on)}		-	5	10			
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_{L} = 15 \Omega$	-	5	10			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.2 \text{ A}, V_{GEN} = 8 \text{ V}, R_g = 1 \Omega$	-	11	25			
Fall Time	t _f		-	5	10			
Drain-Source Body Diode Characteristi	cs							
Continuous Source-Drain Diode Current	Is	T _C = 25 °C	-	-	1 °	^		
Pulse Diode Forward Current	I _{SM}		ı	-	1.4	A		
Body Diode Voltage	V_{SD}	I _S = 0.2 A, V _{GS} = 0 V	-	0.8	1.2	V		
Body Diode Reverse Recovery Time	t _{rr}		-	11	25	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 0.2 A, dl/dt = 100 A/μs, T _J = 25 °C	1	3.5	7	nC		
Reverse Recovery Fall Time	t _a	$I_{\rm F} = 0.2$ A, $\alpha I/\alpha I = 100$ A/ μ s, $I_{\rm J} = 25$ °C	-	5.3	-	ns		
Reverse Recovery Rise Time	t _b		-	5.7	-			

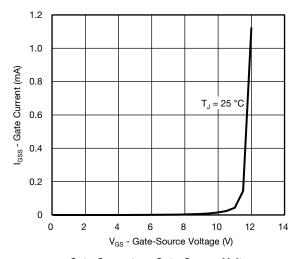
Note

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Surface mounted on 1" x 1" FR4 board with full copper, t = 5 s.

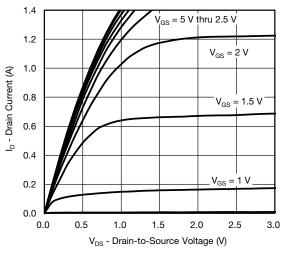
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



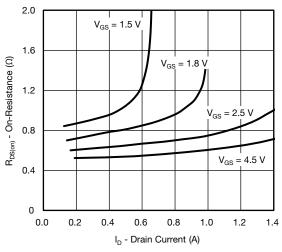
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted



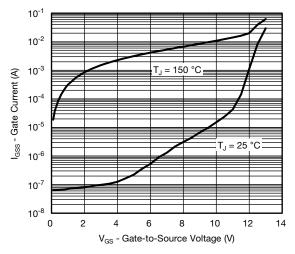
Gate Current vs. Gate-Source Voltage



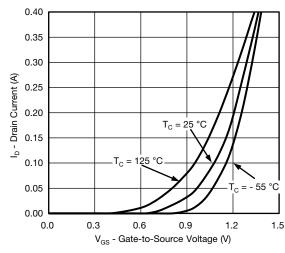
Output Characteristics



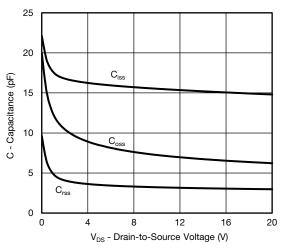
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



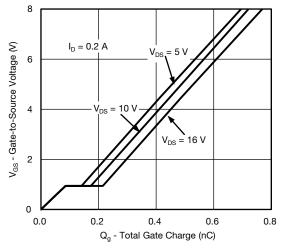
Transfer Characteristics



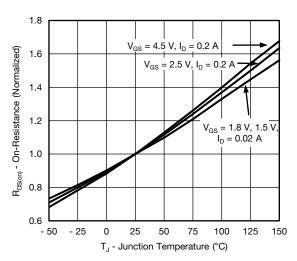
Capacitance vs. Drain-to-Source Voltage



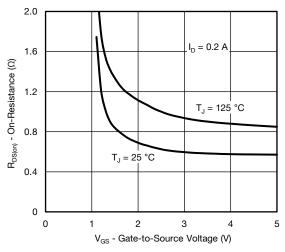
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



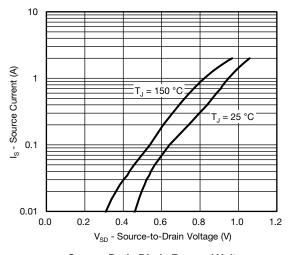
Gate Charge



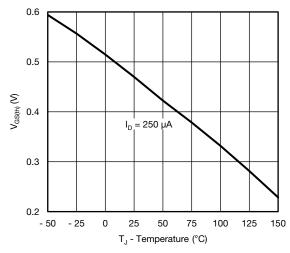
On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage



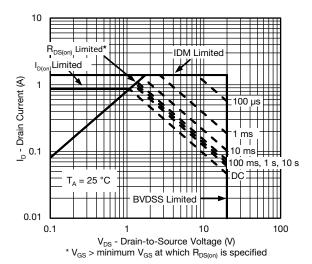
Source-Drain Diode Forward Voltage



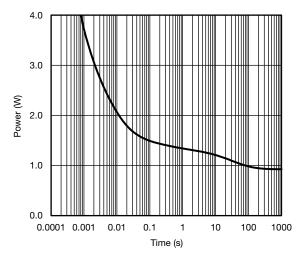
Threshold Voltage



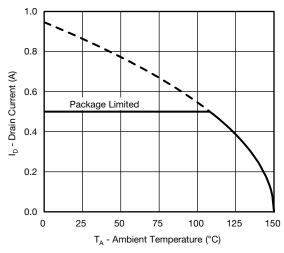
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



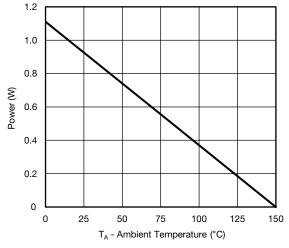
Safe Operating Area (Junction-to-Ambient) a



Single Pulse Power, Junction-to-Ambient ^a



Current Derating a, b



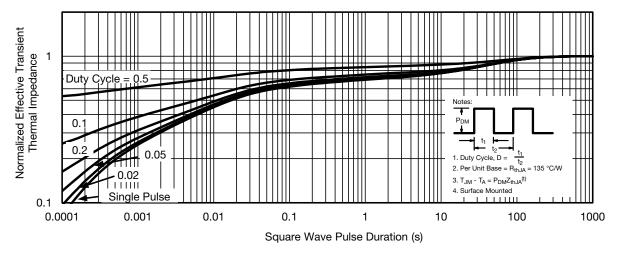
Power Derating a

Note

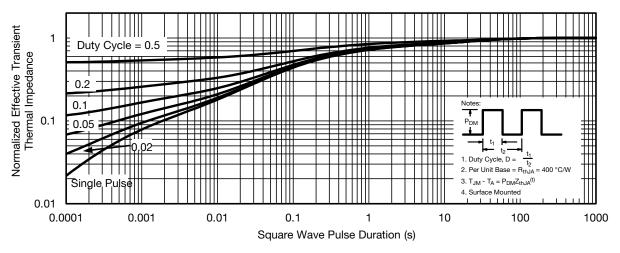
- a. When mounted on 1" x 1" FR4 with full copper.
- b. The power dissipation P_D is based on T_J (max.) = 150 °C, using junction-to-ambient thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient (On 1" x 1" FR4 board with maximum copper)

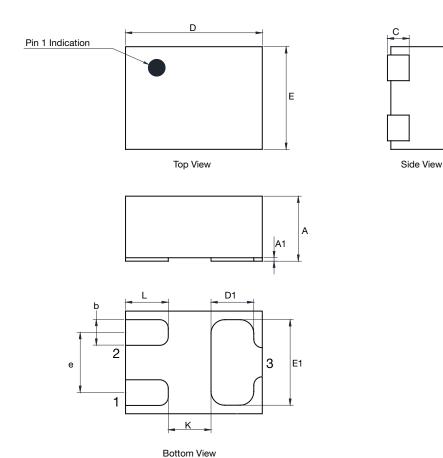


Normalized Thermal Transient Impedance, Junction-to-Ambient (on 1" x 1" FR4 board with minimum copper)

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg262968.



Case Outline for PowerPAK 0.8 mm x 0.6 mm



	MILLIMETERS			INCHES		
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
А	0.350	0.380	0.400	0.0138	0.0150	0.0157
A1	0	-	0.020	0	-	0.0008
b	0.120	0.150	0.180	0.0047	0.0059	0.0071
С	0.119	0.127	0.135	0.0047	0.0050	0.0053
D	0.750	0.800	0.850	0.0295	0.0315	0.0335
D1	0.200	0.250	0.300	0.0078	0.0098	0.0118
E	0.550	0.600	0.650	0.0217	0.0236	0.0256
E1	0.450	0.500	0.550	0.0177	0.0197	0.0217
е	0.300	0.350	0.400	0.0118	0.0138	0.0158
K	0.150	0.250	0.350	0.0058	0.0098	0.0138
Ĺ	0.200	0.250	0.300	0.0078	0.0098	0.0118

ECN: C13-1574-Rev. A, 23-Dec-13

DWG: 6020



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